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(54) **POLISHING PAD**

(57) Abstract:

**PROBLEM TO BE SOLVED:** To provide a polishing pad having an appropriate hardness, good durability, less water absorptiveness, and capable of being molded into various shapes easily.

**SOLUTION:** The polishing pad for the surface of a substance is formed from a resin consisting of an open

ring polymer prepared through metathesis polymerization of ring-form olefin, wherein the resin has a thermal deformation temperature of 90-135°C, a compression modulus of elasticity of 980-2940 MPa, and a water absorptiveness of 0.01-0.25 wt.%, and the resultant pad has an appropriate hardness, good durability and less water absorptiveness, and is unlikely to damage the surface of the substance to be polished.

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